

About Presenters

Terry Ng

- Lead Material Scientist at LPMS USA and a frequent presenter on material innovations for Low Pressure Molding Technologies.
- Member of IPC, WHMMA, American Chemical Society and the Society of Plastics Engineers. He is contributor to the IPC standards task group writing the 2023 updates for the technology.
- Led a cooperative effort among material suppliers to increase the use of additives and fillers to achieve material properties to meet tomorrow's demanding needs.
- University of Connecticut graduate with B.S.E. and M.S. in Materials Science and Engineering

Michael Pierce

- Lead Polymer Chemist at LPMS USA
- Considered one of the global experts in Low Pressure Molding Technologies with hot melt adhesives.
- Member of IPC task force that authored the first standards for Low Pressure Molding
- More than two decades at Henkel Corporation as a polymer chemist and LPM global technical leader.
- Michael is a member of IPC, WHMMA, American Chemical Society and the Society of Plastics Engineers.
- B.S. in Chemistry from Loyola University Chicago and an M.S. in Analytical Chemistry from Governors State University.

Topic	Sub-Topic	Time (min)
I. Introduction		5
II. Electronic and Electronic Boards Protection		15
III. LPM Overview	Intro to LPM	10
	Materials for LPM	5
	Process for LPM	10
IV. Applications for LPM		5
V. Case Studies		5
VI. Conclusion		5
Demo &		40
Q&A		20
	Total time	120 minutes

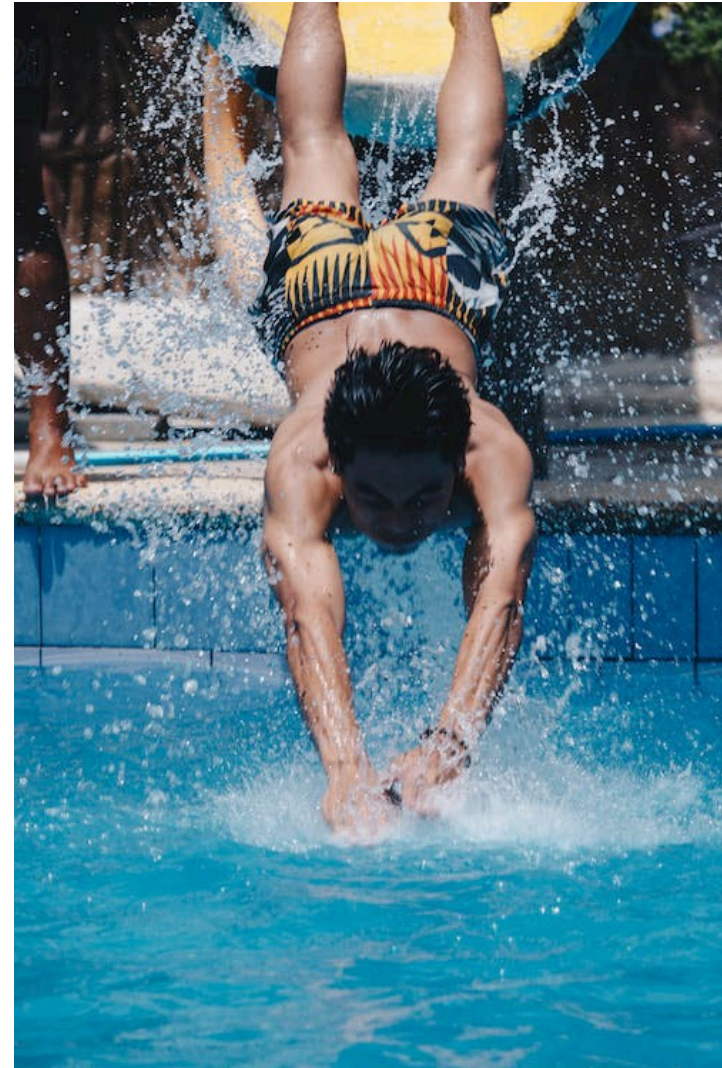
Reliability in Electronics: Encapsulation Techniques & Low Pressure Molding

- The Assembly Show South
- April 4, 2023



Why Protect Electronics?

- Safety
- Reliability
- Cost



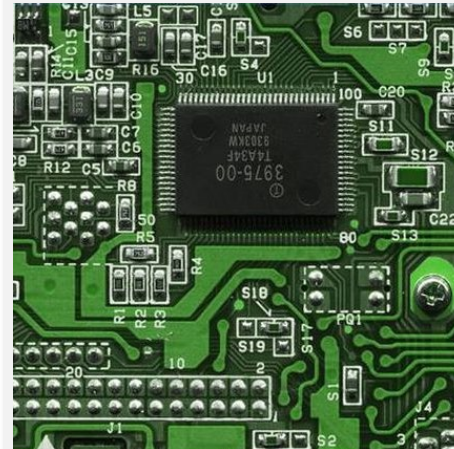
Electronics Protection

What happens without?



- Moisture damage
- Contamination
- Corrosion

Why do we need?



- Ensure reliability
- Environmental resistance
- Chemical resistance
- Cost of repair or replace









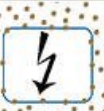
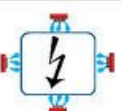
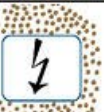
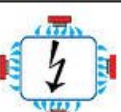
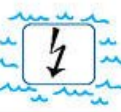
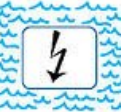

How can we protect?



- Clam Shell
- Potting
- Conformal Coating
- Gasket Sealing
- Low Pressure Molding

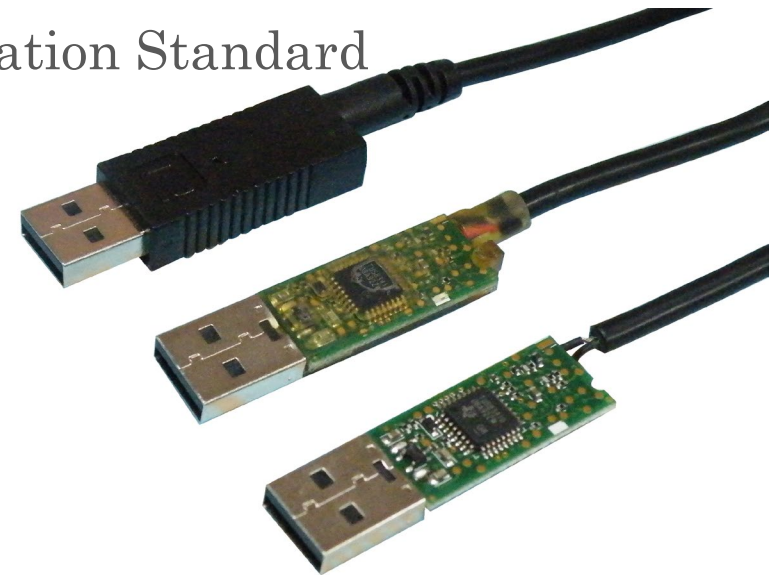
Level of Sealing

- Most products rated using the Ingress Protection (IP) scale
- Degrees of Protection:
 - First Number: protection against solids
 - Second Number: protection against liquids

1st Digit	Protection Against Solids	2nd Digit	Protection Against Liquids
0	No Protection	0	No Protection
1	 Protected against solid objects greater than 50 mm	1	 Protected against vertically falling drops of water
2	 Protected against solid objects greater than 12 mm	2	 Protected against direct sprays of water up to 15° from the vertical
3	 Protected against solid objects greater than 2.5 mm	3	 Protected against direct sprays of water up to 60° from the vertical
4	 Protected against solid objects greater than 1 mm	4	 Protected against water sprays from all directions - limited ingress permitted
5	 Dust protected	5	 Protected against low pressure jets of water from all directions - limited ingress permitted
6	 Dust tight	6	 Protected against strong pressure jets of water from all directions - limited ingress permitted
		7	 Protected against water immersion between 15 cm and 1 m for a duration of 30 minutes
		8	 Protected against continuous immersion in water
		9K	 Protected against close-range, high pressure, high temperature spray downs

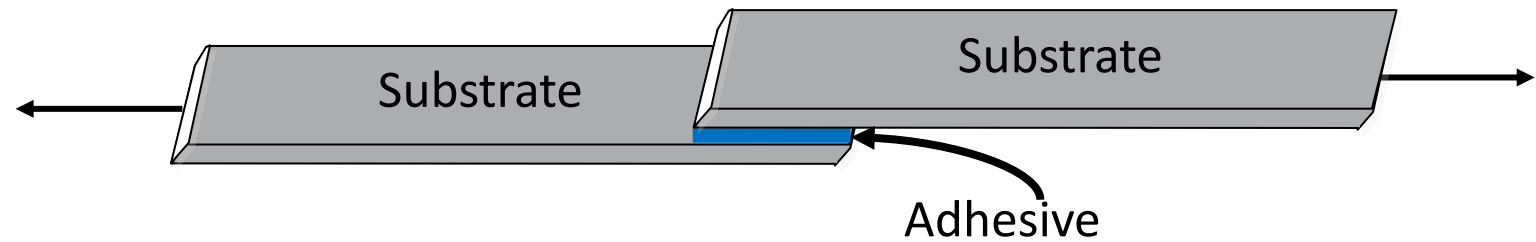
IPC Standards

- Standard for Potting and Encapsulation
- IPC 7621 standard for Low Pressure Molding
 - Created in 2013
- IPC HDBK 850 historical Potting and Encapsulation Standard
 - 2023 update will encompass updated IPC 7621

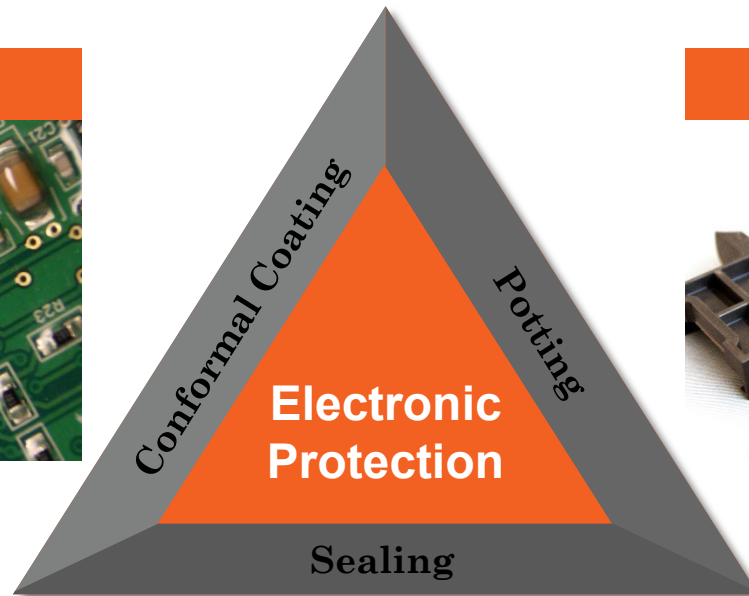
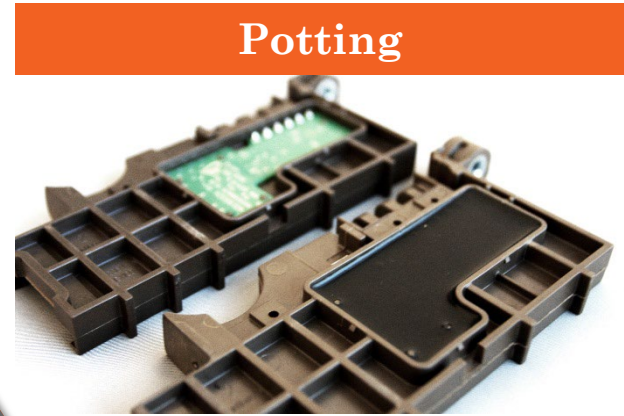


What's Different?

- Dispense style
- Time
- Energy consumption
- Chemical
- Adhesion
 - Enclosure
 - Mechanical bond
 - Chemical bond



Traditional Methods



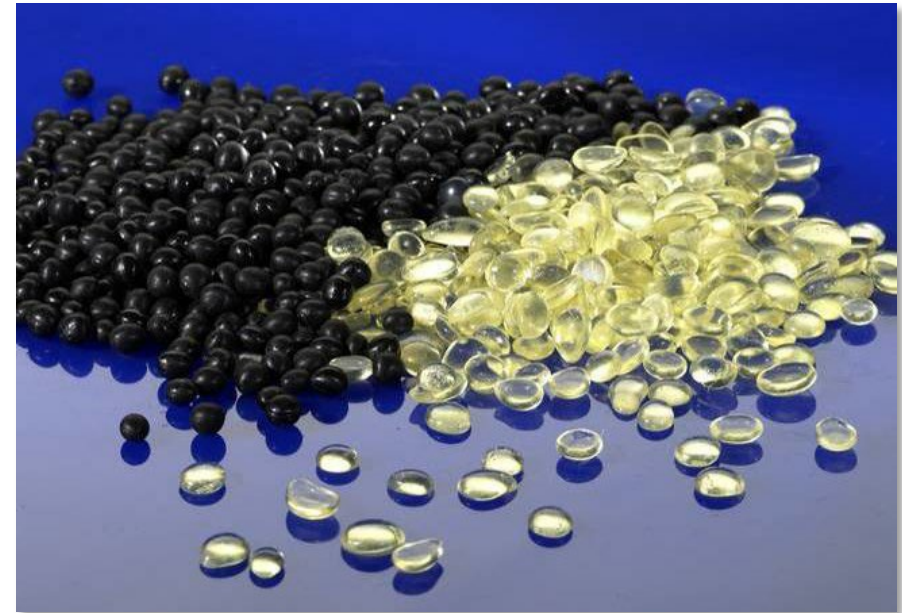
What is the Right Technology for you?

- Understanding the surface
- Understanding the IP rating
- Aesthetic requirements
- Weight, colors, feel
- Cost



Adhesives

- Acrylic adhesives
- Epoxy adhesives
- Cyanoacrylate adhesives
- Polyurethane adhesives
- Silicone adhesives
- Heat-activated adhesives
- Low pressure molding (LPM) adhesives



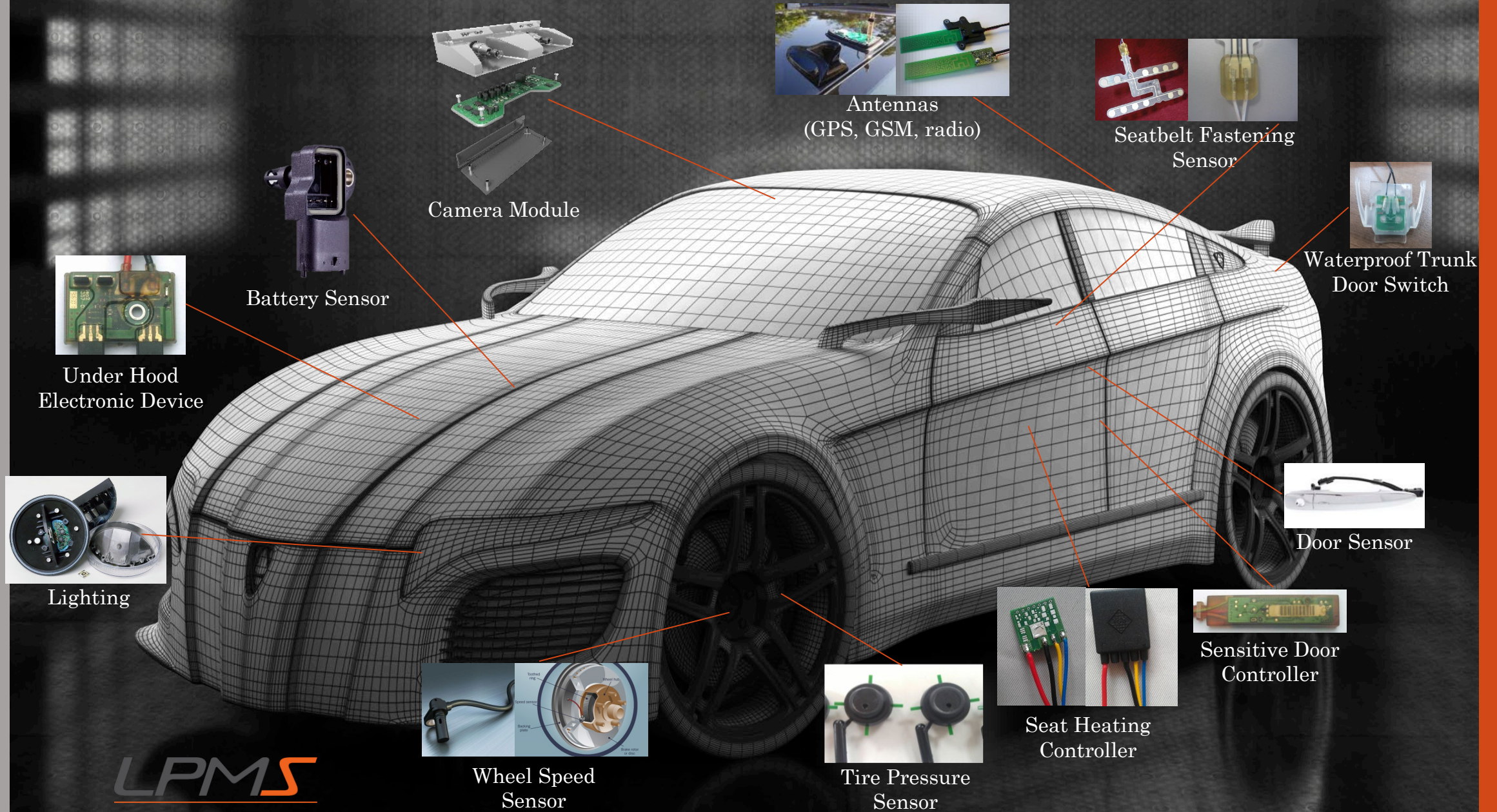
The LPM method

- LPM saves your rice for eating, not drying!



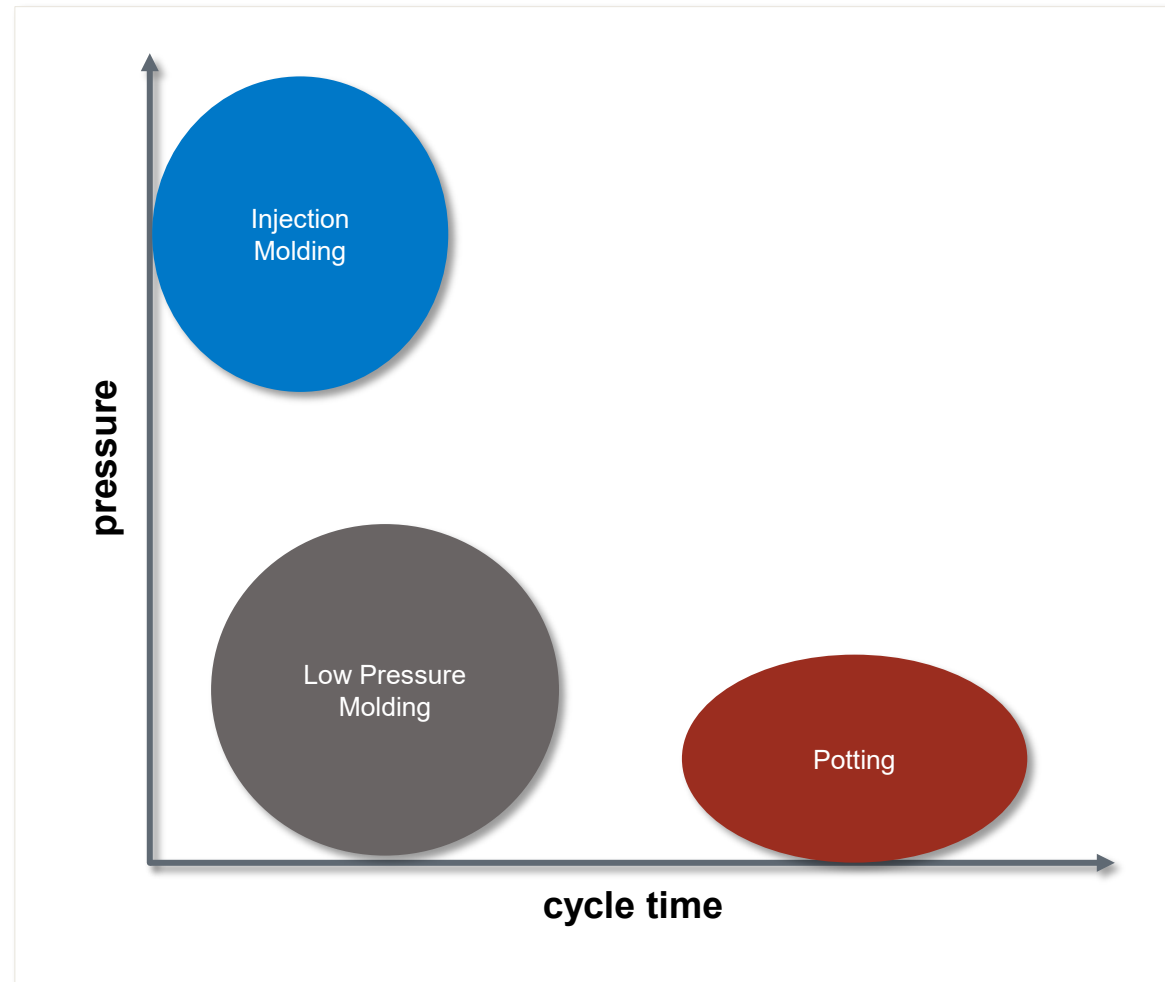
But I don't want to be the first one to try...



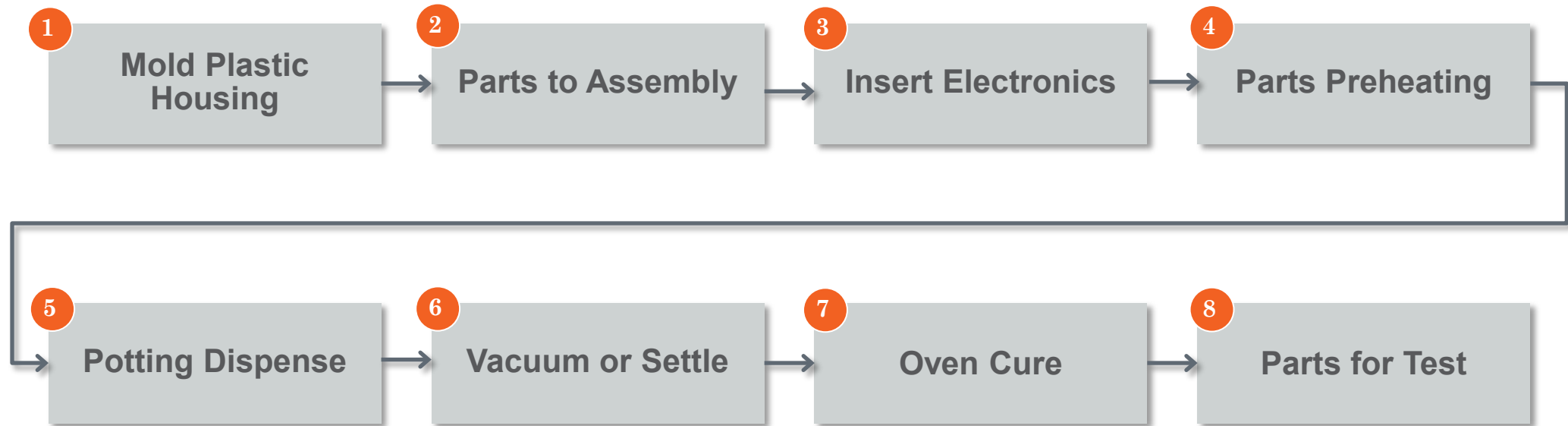


LPM Compared to the other Technologies

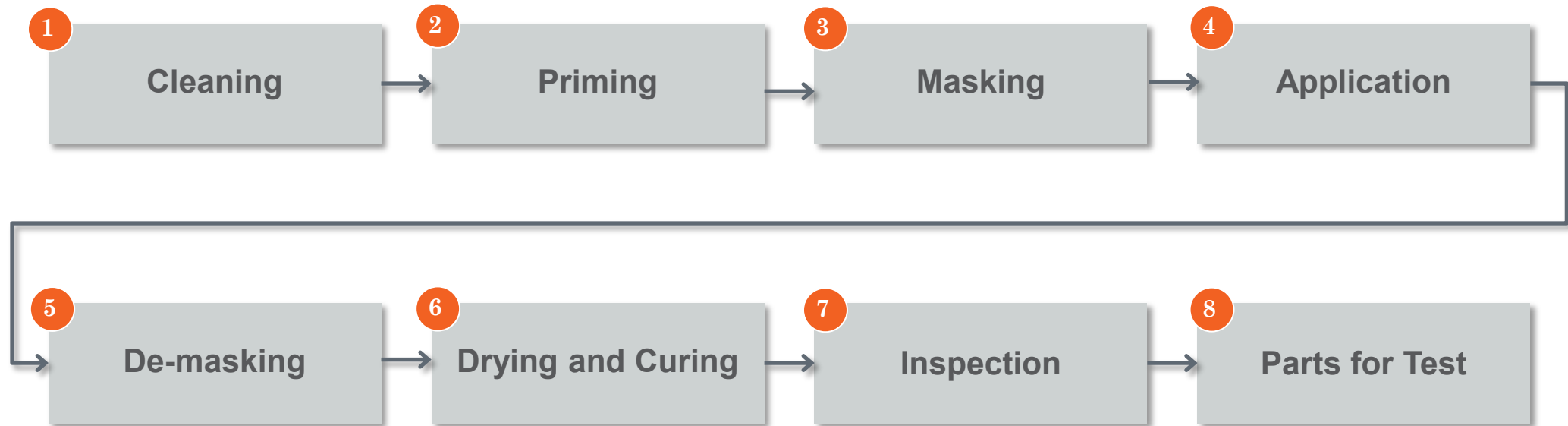
- Hotmelt adhesive!
- Doesn't need to cure
- Reworkable
- Cost effective
- Structural
- Non-hazardous
 - REACH
 - RoHS
 - Prop 65
 - no VOC



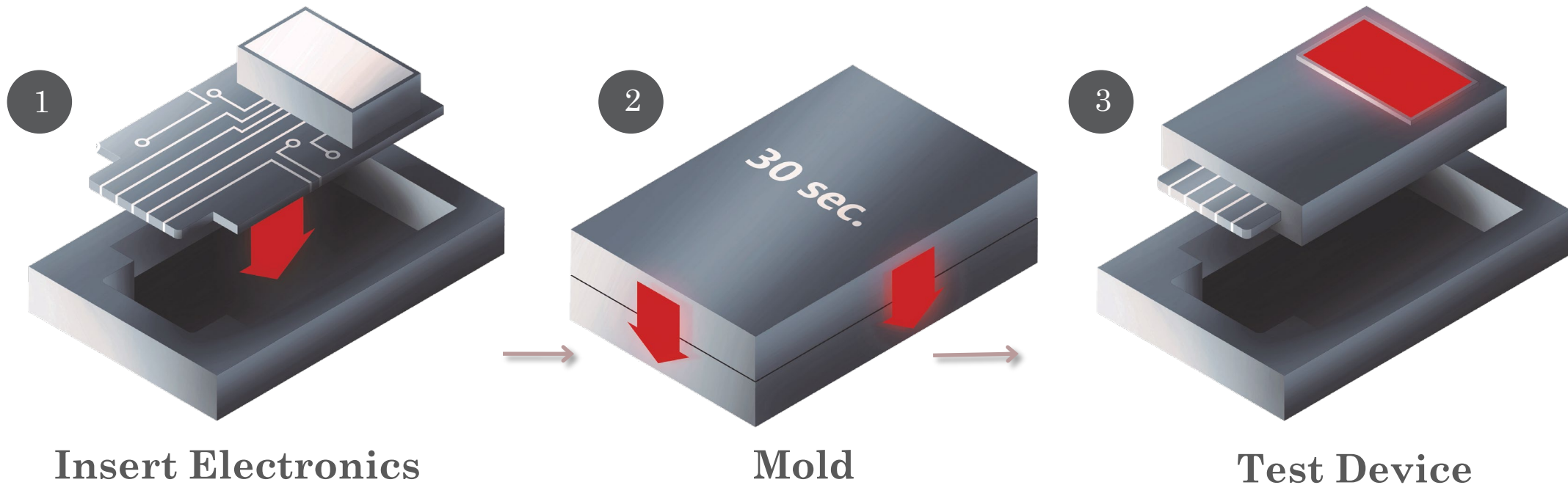
Potting Process Flow



Conformal Coating Process Flow



LPM Process Flow



Materials used in LPM

- **Polyamide**
 - -40 to 150°C
- **Polyolefin**
 - Low hygroscopic
- **Polyester**
 - Low temp flexibility, rubber-like
- Greener technology
- Renewable resources
- Lower carbon footprint
- Smaller waste stream

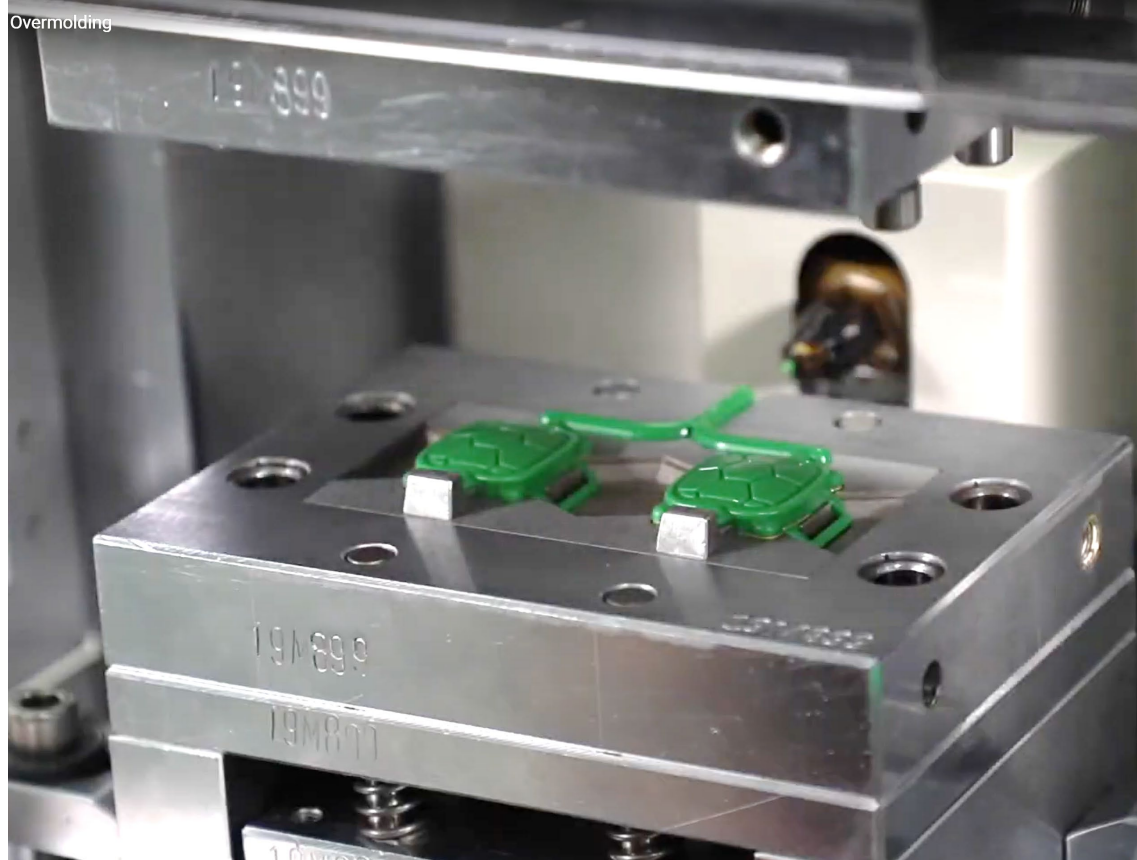


Equipment

- Static melt tank
- Gear pump technology
 - Low viscosity
- Small equipment footprint
- Horizontal/vertical machines
- Multiple nozzle optional



LPM molding video



Low pressure molding of a turtle

Bay Bridge in San Francisco

Situation



1000s of LED lights were installed on the bridge and programmed for a unique light show.

Challenge



- UV stable
- Resistance to salt, fog, humidity, wide range of weather conditions
- Waterproof
- Long operating life

Solution



- Excellent UV and thermal stability
- Resistance to salt, fog and humidity
- Exceptional adhesion

Disney Magic Bands

Situation



Disney World launched bracelets that stored guests' personal data and could be worn throughout an entire vacation.

Challenge



- Adhesion to flex circuit with RFID antenna and data chip
- Fast processing
- Water proof
- Humidity resistant
- Chemical resistant to soap, sunscreen, sweat, etc.

Solution



- High flexibility
- Good chemical and humidity resistance

Deep Water Horizon Oil Spill in the Gulf of Mexico

Situation



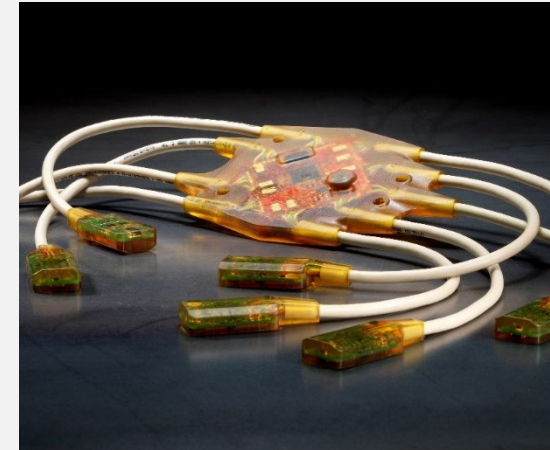
After a few failed attempts to seal the well, an ROV driller was deployed to repair the pipe and install a new blowout preventer to pump in heavy mud to kill the well. There were 10 individual PCBs that required encapsulation, including 9 robot arms.

Challenge



- Fluctuating pressure changes
 - Sustain 2,280 PSI for 3 days
- Salt water
- Hydrocarbon
- Low temperatures
- Mechanical stress and flexibility of robot
- Fast prototyping

Solution



- Best low temperature flexibility and chemical resistance
- High hardness and temperature resistance

Reliability testing



A recap...

- Efficient
- Reliable
- Environmental friendly
- Cost effective



Demonstration

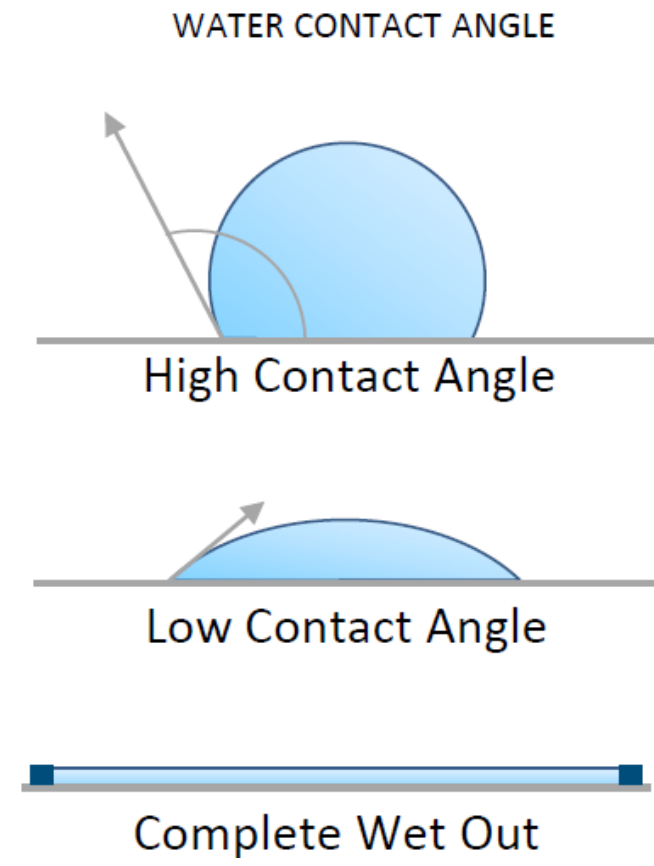
Question?

Adhesion Theory

- Mechanical theory: This theory explains adhesion as a result of mechanical interlocking between two surfaces. When two surfaces are brought into contact, their roughness and irregularities can interlock like two puzzle pieces, creating a bond.
- Electrostatic theory: This theory explains adhesion as a result of electrostatic forces between two surfaces. Opposite charges attract each other, so if two surfaces have different charges, they can be attracted to each other, creating a bond.
- Adsorption theory: This theory explains adhesion as a result of chemical bonding between two surfaces. When two surfaces are brought into contact, their molecules can interact chemically, creating a bond.
- Diffusion theory: This theory explains adhesion as a result of atoms or molecules diffusing between two surfaces. When two surfaces are brought into contact, the atoms or molecules in one surface can diffuse into the other surface, creating a bond.
- Wetting theory: This theory explains adhesion as a result of the ability of a liquid to spread over a surface. When a liquid is brought into contact with a surface, it can wet the surface, creating a bond.

The Science of Surface

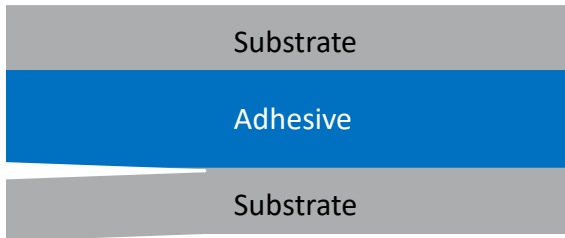
- Concept of wet out



Types of Failures



Cohesive Failure



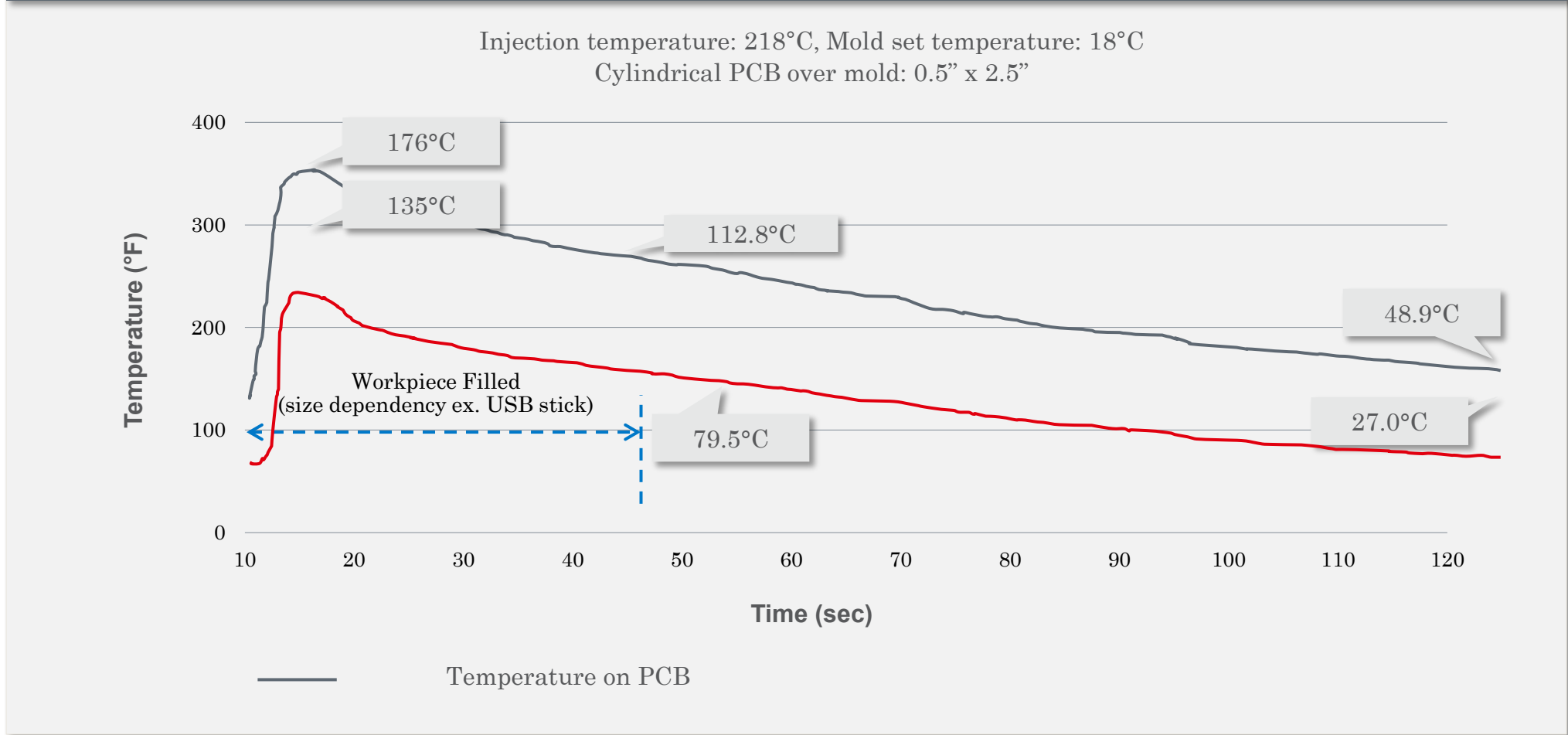
Adhesive Failure



Substrate Failure

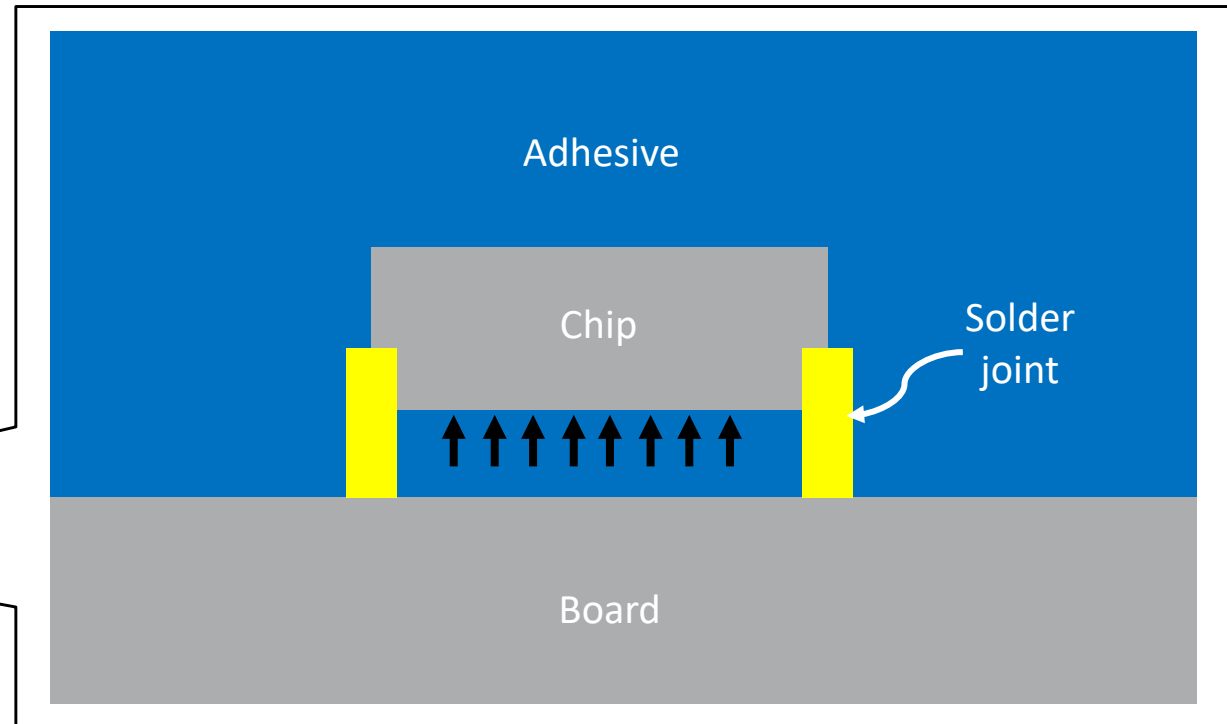
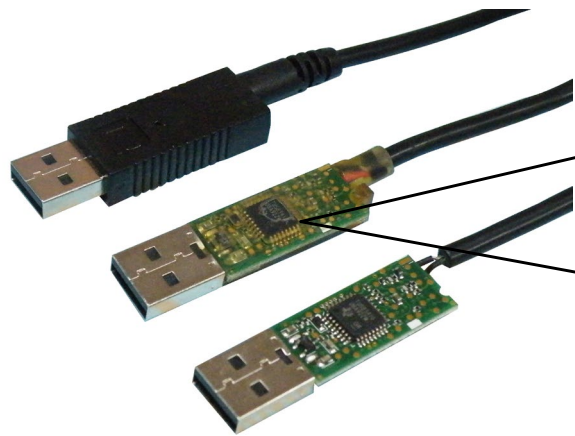
Inside the Mold

Typical Temperature Profile during Injection

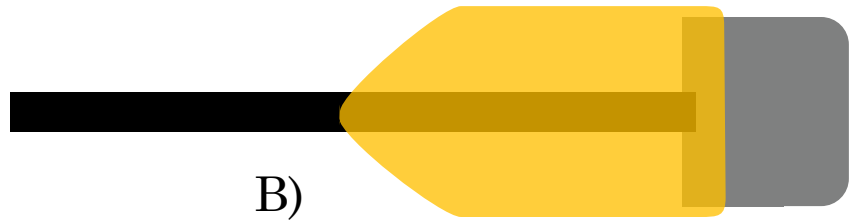


Coefficient of Thermal Expansion

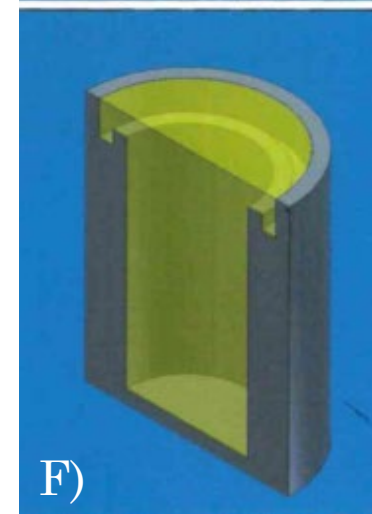
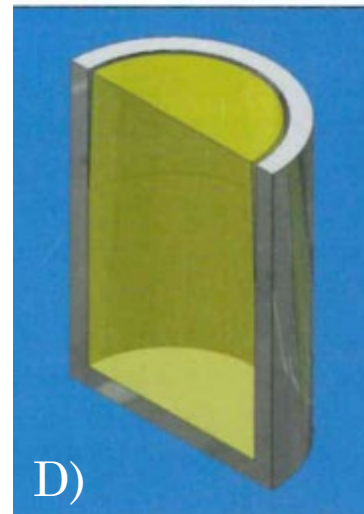
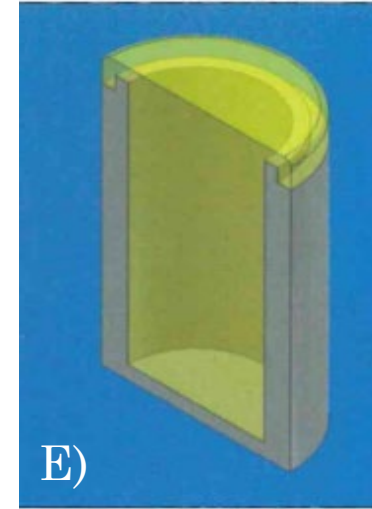
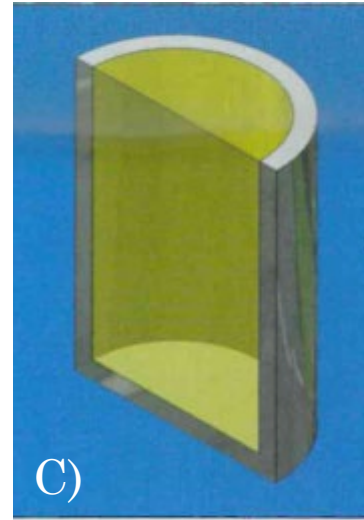
- $CTE = (\Delta L / L_0) / \Delta T$



Design Considerations



- Sharpe edges
- Draft angles
- Part thickness
- Skylining



Design Considerations Cont.

- Tolerance
 - Shrinkage of LPM
 - Insert tolerance
- Color
- Pad printing/laser printing
- Air vent
 - Different from traditional injection molding
 - Inserts
 - Sharp edges
- Runner location
- # cavities



Common Test on Adhesives

- Lap shear
- Peel test
- Tape test
- Tensile test
- Thermal cycle test
- Others...



Future of LPM

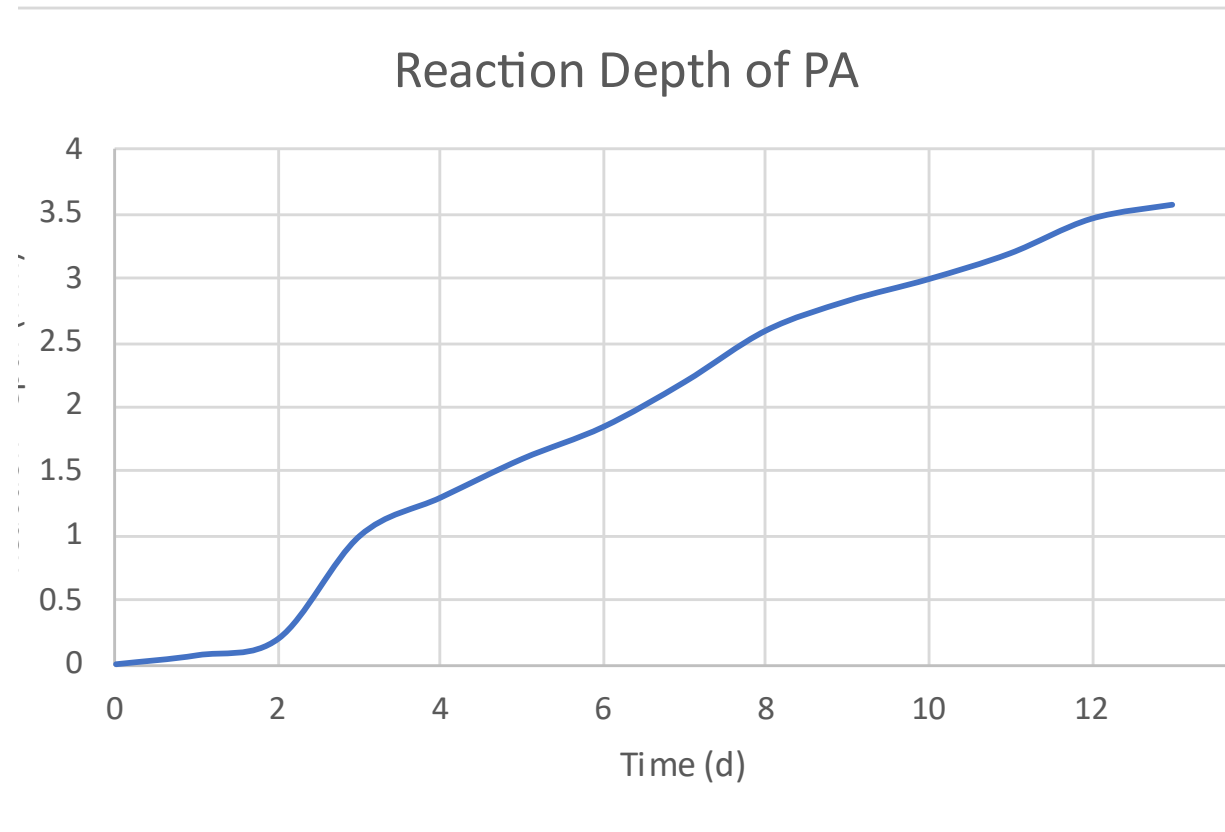
- Specialized materials for different need
- Filler additives and reactive technologies
- Typically need specialized equipment for dispensing but still in low pressure regime

Thermally Conductive

- High temperature resistivity
 - Stable to 200 °C
- Moisture reactive
- Delayed to full strength

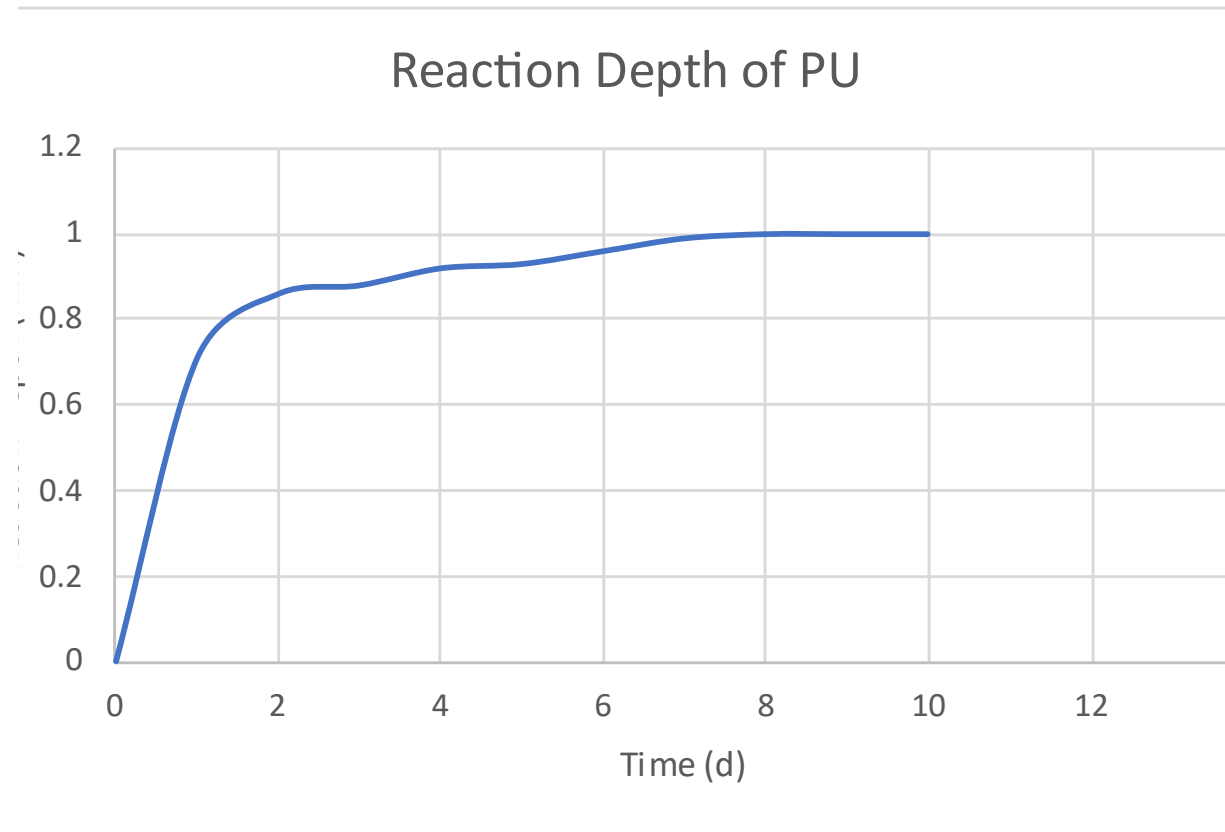
Post-crosslinking PA

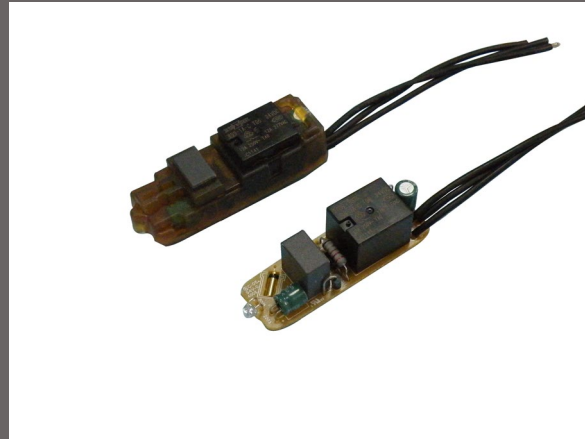
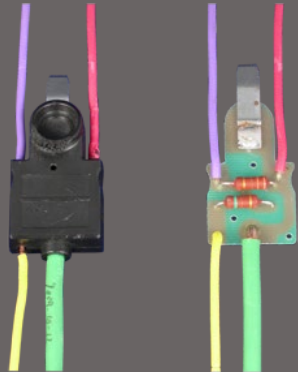
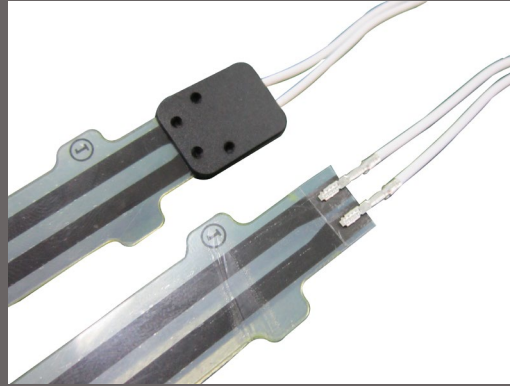
- High temperature resistivity
 - Stable to 200 °C
- Moisture reactive
- Delayed to full strength



Post-crosslinking PU

- Low temperature usage
- Moisture reactive
- Delayed to full strength
- Stable to 80°C





Overmolding
Pictures

